

DATA SHEET

High-voltage SC type: NP0/X7R X I / Y 2 & X 2 / Y 3 2 pF to 1.5 nF



YAGEO Phi(comp



SCOPE

This specification describes safety certification NP0/X7R series chip capacitors with lead-free terminations.

APPLICATIONS

- PCs, Notebook
- Networking
- Power supplies

FEATURES

- Supplied in tape on reel
- Nickel-barrier end termination
- RoHS compliant
- Halogen Free compliant

ORDERING INFORMATION-GLOBAL PART NUMBER, PHYCOMP CTC & <u>12NC</u>

All part numbers are identified by the series, size, tolerance, TC material, packing style, voltage, process code, termination and capacitance value. Please note that 12 digits ordering code will expire at the end of 2010.

YAGEO BRAND ordering codes **GLOBAL PART NUMBER (PREFERRED)**

<u>xxxx x x xxx x</u> B <u>x xxx</u> (2) (3) (4) (5) (I) (6) (7)

(I) SIZE - INCH BASED (METRIC)

1808 (4520)

1812 (4532)

(2) TOLERANCE

 $C = \pm 0.25 pF$

 $D = \pm 0.5 pF$

 $J = \pm 5\%$

 $K = \pm 10\%$

(3) PACKING STYLE

K = Blister taping reel; Reel 7 inch

(4) TC MATERIAL

NPO

X7R

(5) IMPULSE VOLTAGE

T = X2/Y3 for TUV/UL

W= XI/Y2 for TUV/UL

U = XI for UL (1812 X7R)

(6) PROCESS

N = NP0

B = Class 2 product

(7) CAPACITANCE VALUE

2 significant digits+number of zeros

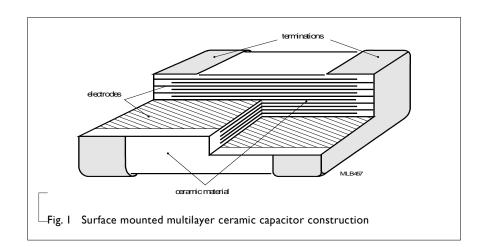
The 3rd digit signifies the multiplying factor, and letter R is decimal point

Example: $121 = 12 \times 10^{1} = 120 \text{ pF}$

CONSTRUCTION

The capacitor consists of a rectangular block of ceramic dielectric in which a number of interleaved metal electrodes are contained. This structure gives rise to a high capacitance per unit volume.

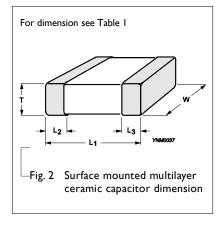
The inner electrodes are connected to the two end terminations and finally covered with a layer of plated tin (NiSn). The terminations are lead-free. A cross section of the structure is shown in Fig.I.



DIMENSION

lable 1 For outlines see fig. 2		
TYPE	SC1808	SC1812
L ₁ (mm)	4.8 ±0.30	4.8 ±0.30
W (mm)	2.0 ±0.30	3.2 ±0.30
T (mm)	Refer to table 2 to	3
L ₂ /L ₃ (mm) min.	0.25	0.25
L ₂ /L ₃ (mm) max.	0.75	0.75

OUTLINES





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CAPACITANCE RANGE & THICKNESS FOR NP0 X1/Y2 AND X2/Y3

Table 2 Sizes from 1808 to 1812

CAPACITANCE	1808, X1/Y2 TUV	1808, X1/Y2 UL	1808, X2/Y3 TUV/UL	1812, X1/Y2 TUV/UL
I5 pF				
18 _P F				
22 pF				
27 pF				
33 pF	14.00	14.00		
39 _P F	1.6±0.2	1.6±0.2		1.6±0.2
47 pF			1.6±0.2	
56 pF				
68 _P F				
82 pF				
100 _P F				
120 pF				
150 _P F		2.0±0.2		
180 _P F				
220 pF	2.0±0.2			
240 pF				2.0±0.2
270 pF				2.0±0.2
330 pF				
390 pF			2.0±0.2	
430 _P F			2.010.2	
470 pF				
560 _P F				
680 _P F				
820 _P F				
1000 _P F				

NOTE

- I. Values in shaded cells indicate thickness class in mm
- 2. Capacitance value of non E-12 series is on request



CAPACITANCE RANGE & THICKNESS FOR X7R X1/Y2 AND X2/Y3

—Table 3	Sizes 1	from	1808	to	1812
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CAPACITANCE	1808, X1/Y2	1808, X2/Y3	1812, X1/Y2	1812, XI
C, II / ICI / II ICE	TUV/UL	TUV/UL	TUV	UL
150 pF				
180 pF	1.6±0.2			
220 pF				
240 pF			14.00	14.00
270 pF		14.00	1.6±0.2	1.6±0.2
330 pF		1.6±0.2		
390 pF				
430 pF	20.02			
470 pF	2.0±0.2			
560 pF				
680 pF			2.0±0.2	2.0±0.2
820 pF				
1.0 nF		2.0±0.2		
1.2 nF				
1.5 nF				

NOTE

THICKNESS CLASSES AND PACKING QUANTITY

—Table 4

DESCRIPTION	SIZE	THICKNESS CLASSIFICATION	12 mm TAPE WIDTH /AMOUNT PER REEL
	CODE	(mm)	Ø180 mm, 7" Blister
	1808	1.6 ±0.20	2,000
Safety Certification		2.0 ±0.20	2,000
Capacitor	1812	1.6 ±0.20	1,000
•		2.0 ±0.20	1,000

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ELECTRICAL CHARACTERISTICS

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NP0/X7R DIELECTRIC CAPACITORS; NISN TERMINATIONS

Unless otherwise stated all electrical values apply at an ambient temperature of 20±1 °C, an atmospheric pressure of 86 to 106 kPa, and a relative humidity of 63 to 67%.

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DESCRIE	PTION	VALUE
Capacitance range		2 pF to 1.5 nF
Capacita	nce tolerance	
NP0	C < 10 pF	±0.25 pF, ±0.5 pF
	C ≥ 10 pF	±5%
X7R		±10%
Dissipation	on factor (D.F.)	
NP0	C < 30 pF	≤ I / (400 + 20C)
	C ≥ 30 pF	≤ 0.1 %
X7R		≤ 2.5 %
Insulation	n resistance after 1 minute at U _r (DC)	$R_{ins} \ge 10 \text{ G}\Omega \text{ or } R_{ins} \times C \ge 500 \text{ seconds whichever is less}$
	n capacitance change as a function of temperature ature characteristic/coefficient):	
NP0		±30 ppm/°C
X7R		±15%
-	ng temperature range:	
NP0/X	/K	–55 °C to +125 °C

CAPACITOR REQUIREMENT

Table 6

SAFETY RATING	VOLTAGE RATING	WITHSTANDING VOLTAGE	IMPULSE VOLTAGE
ΧI	250 VAC	1,500 VAC	4,000 V
X2	250 VAC	1,500 VAC	2,500 V
Y2	250 VAC	1,500 VAC	5,000 V
Y3	250 VAC	1,500 VAC	

SOLDERING RECOMMENDATION

-Table 7

SOLDERING METHOD	SIZE 0402	0603	0805	1206	≥ 1210
Reflow	≥ 0.1 µF	≥ 1.0 µF	≥ 2.2 µF	≥ 4.7 µF	Reflow only
Reflow/Wave	< 0.1µF	< 1.0 µF	< 2.2 µF	< 4.7 µF	



TESTS AND REQUIREMENTS

Table 8 Test procedures and requirements

TEST TEST METHO		HOD	PROCEDURE	REQUIREMENTS	
Mounting	IEC 60384- 21/22	4.3	The capacitors may be mounted on printed-circuit boards or ceramic substrates	No visible damage	
Visual Inspection and Dimension Check		4.4	Any applicable method using × 10 magnification	In accordance with specification	
Capacitance		4.5.1	NP0: $f = I \text{ MHz for } C \leq I \text{ nF, measuring at voltage } I \text{ V}_{rms} \text{ at } 20 \text{ °C;} \\ f = I \text{ KHz for } C > I \text{ nF, measuring at voltage } I \text{ V}_{rms} \text{ at } 20 \text{ °C} \\ \text{X7R:} \\ f = I \text{ KHz for } C \leq I0 \mu\text{F, measuring at voltage } I \text{ V}_{rms} \text{ at } 20 \text{ °C} \\ \end{cases}$	Within specified tolerance	
Dissipation Factor (D.F.)		4.5.2	NP0: $f = 1 \text{ MHz for } C \le 1 \text{ nF, measuring at voltage I } V_{rms} \text{ at } 20 \text{ °C;}$ $f = 1 \text{ KHz for } C > 1 \text{ nF, measuring at voltage I } V_{rms} \text{ at } 20 \text{ °C}$ $X7R:$ $f = 1 \text{ KHz for } C \le 10 \mu\text{F, measuring at voltage I } V_{rms} \text{ at } 20 \text{ °C}$	In accordance with specification	
Insulation Resistance		4.5.3	To apply 500 V max for 60 seconds	In accordance with specification	

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TEST	TEST METI	HOD	PROCEDURE	REQUIREMENTS
Temperature Characteristic		4.6	Capacitance shall be measured by the steps shown in the following table.	<general purpose="" series=""> Class I: Δ C/C: ±30ppm</general>
			The capacitance change should be measured after 5 min at each specified temperature stage.	Class2:
			Step Temperature(°C)	X7R: Δ C/C: ±15%
			a 25±2	Y5V: ∆ C/C: 22~-82%
			b Lower temperature±3°C	<high capacitance="" series=""> Class2:</high>
			c 25±2	X7R/X5R: Δ C/C: ±15%
			d Upper Temperature±2°C	Y5V: ∆ C/C: 22~-82%
			e 25±2	
			(I) Class I	
			Temperature Coefficient shall be calculated from the formula as below	
			Temp, Coefficient = $\frac{\text{C2-C1}}{\text{C1x}\Delta\text{T}} \times 10^6 \text{ [ppm/°C]}$	
			C1: Capacitance at step c	
			C2: Capacitance at 125°C	
			ΔT: 100°C(=125°C-25°C)	
			(2) Class II	
			Capacitance Change shall be calculated from the formula as below	
			$\Delta C = \frac{C2 - C1}{C1} \times 100\%$	
			C1: Capacitance at step c	
			C2: Capacitance at step b or d	
Adhesion		4.15	 a. A force applied for 10 seconds to the line joining the terminations and in a plane parallel to the substrate for size ≥ 0603 : a force of 5N applied 	No visible damage
			b. A force applied until brokenFor size ≥ 0603: ≥ 5N	
Bond Strength of	IEC 60384- 21/22	4.8	Mounting in accordance with IEC 60384-22 paragraph 4.3	No visible damage
Plating on			Conditions: bending I mm at a rate of I mm/s, radius jig	Δ C/C
End Face			340 mm	NP0: ≤ 1% or 0.5 pF
				whichever is greater X7R: ≤ 10%
				X/N. ≥ 10/6
Resistance to Soldering		4.9	Precondition: 150 +0/–10 °C for 1 hour, then keep for 24 ±1 hours at room temperature	The termination shall be well tinned
Heat			Preheating: for size ≤ 1206: 120 °C to 150 °C for 1	ΔC/C
			minute	NP0: ≤ 0.5% or 0.5 pF
			Preheating: for size >1206: 100 °C to 120 °C for I	whichever is greater
			minute and 170 °C to 200 °C for 1 minute Solder bath temperature: 260 ±5 °C	X7R: ≤ 10%
			Joiner Daur Leitiperature, 200 ±3 C	
			Dipping time: 10 ±0.5 seconds	D.F. within initial specified value



TEST	TEST METI	HOD	PROCEDURE	REQUIREMENTS
Solderability		4.10	Unmounted chips completely immersed in a solder bath at 235 ±5 °C Dipping time: 2 ±0.5 seconds Depth of immersion: 10 mm	The termination shall be well tinned
Damp Heat with U _r Load		4.13	Initial measurements; after 150 +0/-10 °C for 1 hour, then keep for 24 ±1 hours at room temperature Duration and conditions: 500 ±12 hours at 40 ±2 °C; 90 to 95% RH; 1.0 Ur applied Final measurement: perform a heat treatment at 150 +0/-10 °C for 1 hour, final measurements shall be carried out 24 ±1 hours after recovery at room temperature without load	$\Delta C/C$ NP0: $\leq 2\%$ or 1 pF whichever is greater X7R: $\leq 15\%$ D.F. NP0: $\leq 2 \times \text{specified value}$ X7R: $\geq 100 \text{V}: \leq 5\%$ Rins NP0: $\geq 2,500 \text{ M}\Omega$ or Rins $\times \text{Cr} \geq 25\text{s}$ whichever is less X7R: $\geq 500 \text{ M}\Omega$ or Rins $\times \text{Cr} \geq 25\text{s}$ whichever is less
Endurance	EN132400	4.14 SC	Perform shear test, substrate bending test, impulse voltage and then endurance test progressively	Visual examination
			Same as the above except for 1.25 Ur for X-capacitor and 1.7 Ur for Y-capacitor	DC/C < ± 20%
			Once every hour the voltage shall be increased to 1000 VAC for 0.1 s	Voltage proof
			Total time take to change over to 1000 VAC and back does not exceed 30 s	IR > 3 ×10E9 Ω
Impulse Voltage		4.13 SC IEC- 60384-14	X1: 4.0 KV, X2: 2.5 KV Y2: 5.0 KV, Y3: None If any three successive impulses are shown by the oscilloscope monitor to have had a waveform indicating that no self-healing breakdowns or flashovers have taken place in the capacitor, then no further impulses shall be applied and the capacitor shall be counted as conforming. 24 impulses have been applied to the capacitor and 3 or more of them are of a waveform indicating that no self-heating breakdowns or flashovers have occurred. Time between impulses shall not be less than 10 s	No breakdown or flashover
Robustness of Termination		4.3 SC	a. A force applied for 10 sec to the line joining the terminations and in a plane parallel to the substrate.	a. No visible damage
(Pull Strength)			b. A force applied until broken	b. Force size \geq 0603: \geq 5N
Voltage Proof		4.2.1 SC	X capacitor: Applied voltage 1.075K VDC (4.3 Ur) Y capacitor: Applied voltage 1.5K VAC	No breakdown or flashover



Surface-Mount Ceramic Multilayer Capacitors | Safety Certification | NPO/X7R | X1/Y2 & X2/Y3

REVISION HISTORY

DATE	CHANGE NOTIFICATION	DESCRIPTION		
Jan. 27, 2015	-	- Capacitance range update		
Dec. 16, 2013	-	- impulse voltage update		
Apr 06, 2011	-	- X2/Y3 UL certification removed		
Oct 20, 2010	-	- Impulse voltage coding rule updated		
Feb 06, 2010	-	- The statement of "Halogen Free" on the cover added		
Oct 30, 2009	-	- Define global part number		
		- Product range updated		
		- Description of "Halogen Free compliant" added		
		- Test method and procedure updated		
Mar I, 2007	-	- New datasheet for high voltage NP0/X7R series with lead-free terminations		
	Jan. 27, 2015 Dec. 16, 2013 Apr 06, 2011 Oct 20, 2010 Feb 06, 2010 Oct 30, 2009	Jan. 27, 2015 - Dec. 16, 2013 - Apr 06, 2011 - Oct 20, 2010 - Feb 06, 2010 - Oct 30, 2009 -		



Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Yageo:

SC1808KKX7RTBB102	SC1812KKX7RWBB102	SC1808KKX7RWBB102	2 SC1812KKX7RWBB152
SC1808JKNPOWBN330	SC1808KKX7RTBB152	SC1808KKX7RTBB221	SC1808KKX7RTBB471
SC1808KKX7RVBB102	SC1808KKX7RWBB681	SC1812JKNPOWBN220	SC1808JKNPOTBN102
SC1808JFNPOWBN330	SC1812KKX7RWBB821	SC1808KKX7RTBB181	SC1808JKNPOWBN221
SC1812JKNPOWBN221	SC1808KKNPOTBN101	SC1812KKX7RWBB221	SC1808JKNPOTBN220
SC1812JKNPOWBN390	SC1808KKX7RTBB151	SC1808JKNPOTBN150	SC1812JKNPOWBN150
SC1812JKNPOWBN121	SC1808JKNPOTBN470	SC1808KKX7RWBB561	SC1812KKX7RWBB681